

## 1. General description

High voltage, high speed planar passivated NPN power switching transistor in a SOT78 (TO-220AB) plastic package.

## 2. Features and benefits

- Fast switching
- Low thermal resistance
- Very high voltage capability
- Very low switching and conduction losses

## 3. Applications

- DC-to-DC converters
- High frequency electronic lighting ballasts
- Inverters
- Motor control systems

## 4. Quick reference data

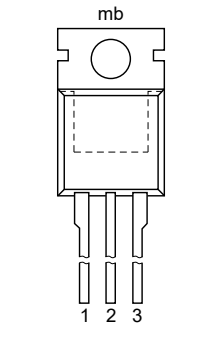
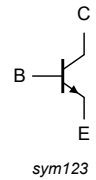
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{CM}$	peak collector current	<a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	-	8	A
$P_{tot}$	total power dissipation	$T_{mb} \leq 25\text{ °C}$ ; <a href="#">Fig. 4</a>		-	-	80	W
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$		-	-	1050	V
<b>Static characteristics</b>							
$h_{FE}$	DC current gain	$I_C = 0.1\text{ A}$ ; $V_{CE} = 5\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 11</a>	<a href="#">[1]</a>	48	66	100	
		$I_C = 0.8\text{ A}$ ; $V_{CE} = 3\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 12</a>	<a href="#">[1]</a>	25	42	50	

[1] Pulse test: pulse duration  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p>TO-220AB (SOT78)</p>	
2	C	collector		
3	E	emitter		
mb	C	mounting base; connected to collector		

## 6. Ordering information

Table 3. Ordering information

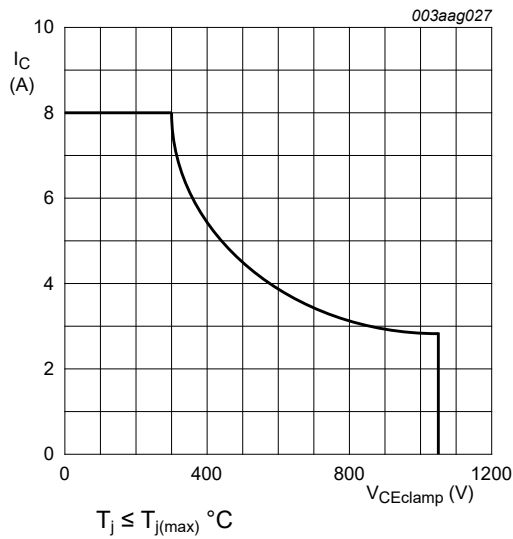
Type number	Package		
	Name	Description	Version
BUJ302A	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 7. Limiting values

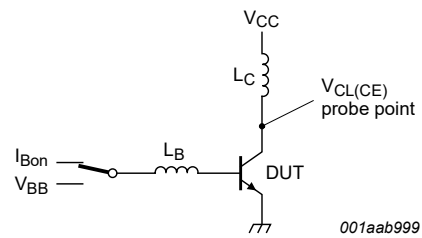
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$	-	1050	V
$V_{CEO}$	collector-emitter voltage	$I_B = 0\text{ A}$	-	400	V
$V_{EBO}$	emitter-base voltage	$I_C = 0\text{ A}; I_E = 2\text{ A}; t_p < 10\text{ ms}$	-	24	V
$I_C$	collector current	<a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	4	A
$I_{CM}$	peak collector current		-	8	A
$I_B$	base current		-	2	A
$I_{BM}$	peak base current		-	4	A
$P_{tot}$	total power dissipation	$T_{mb} \leq 25\text{ °C}$ ; <a href="#">Fig. 4</a>	-	80	W
$T_{stg}$	storage temperature		-65	150	°C
$T_j$	junction temperature		-	150	°C

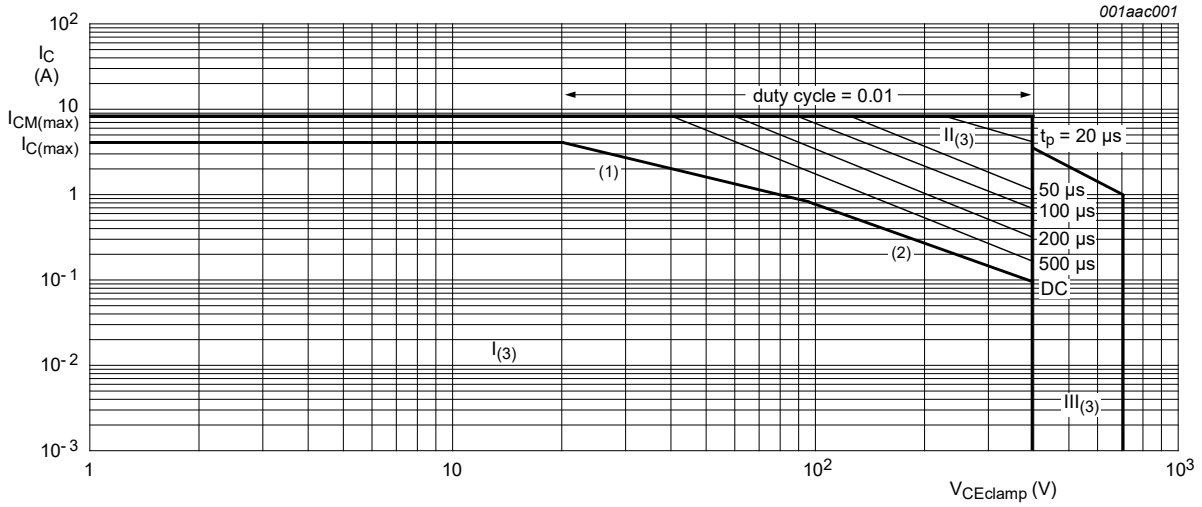


**Fig. 1. Reverse bias safe operating area**



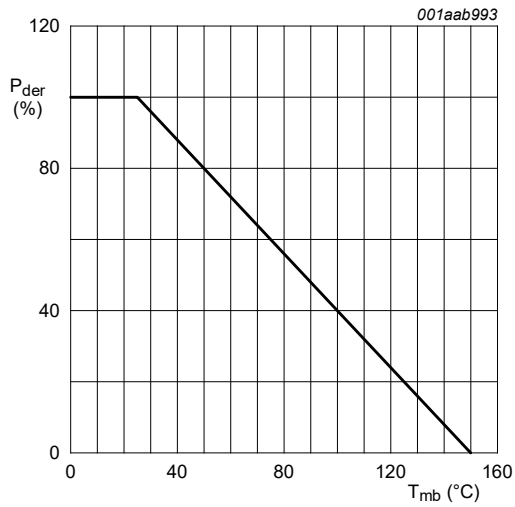
$V_{CL(CE)} \leq 1000\text{ V}$ ;  $V_{CC} = 150\text{ V}$ ;  $V_{BB} = -5\text{ V}$ ;  
 $L_B = 1\text{ }\mu\text{H}$ ;  $L_C = 200\text{ }\mu\text{H}$

**Fig. 2. Test circuit for reverse bias safe operating area**



- 1)  $P_{tot}$  maximum and  $P_{tot}$  peak maximum lines
- 2) Second breakdown limits
- 3) I = Region of permissible DC operation  
 II = Extension for repetitive pulse operation  
 III = Extension during turn-on in single transistor converters provided that  $R_{BE} \leq 100 \Omega$  and  $t_p \leq 0.6 \mu s$

Fig. 3. Forward bias safe operating area for  $T_{mb} \leq 25 \text{ }^\circ\text{C}$



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100 \%$$

Fig. 4. Normalized total power dissipation as a function of mounting base temperature

### 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	1.56	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

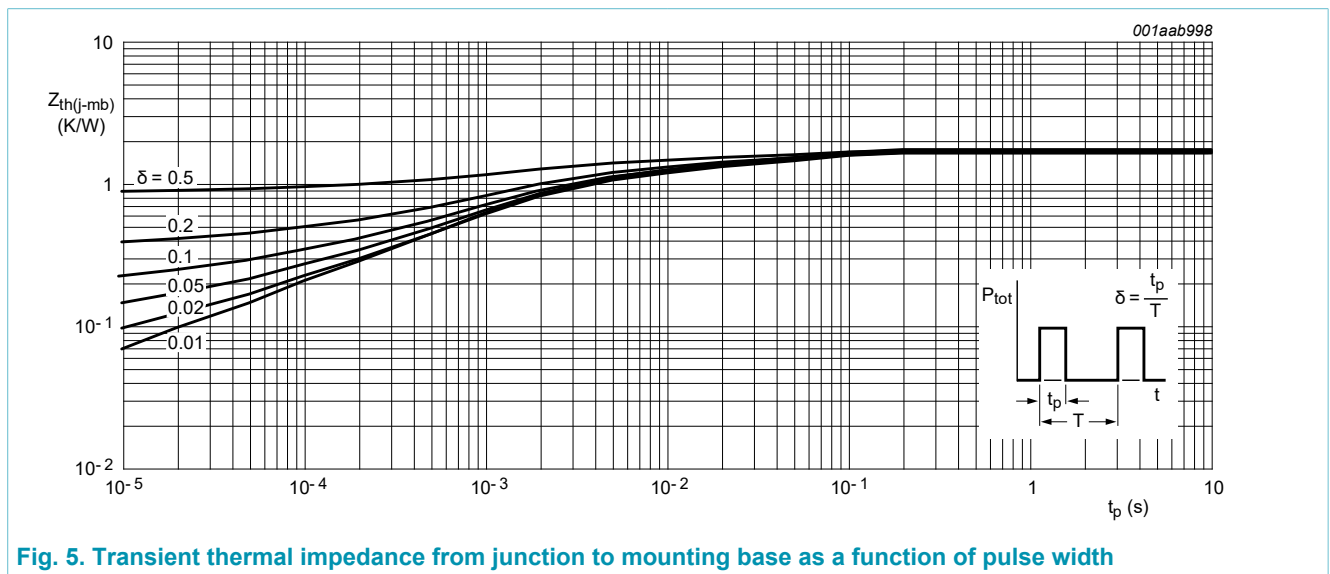


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse width

## 9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Static characteristics</b>							
$I_{CES}$	collector-emitter cut-off current (base shorted)	$V_{BE} = 0\text{ V}$ ; $V_{CE} = 1050\text{ V}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$	-	0.2	10	$\mu\text{A}$	
$I_{CEO}$	collector-emitter cut-off current (base open)	$V_{CE} = 400\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$	-	10	250	mA	
$V_{(BR)EBO}$	emitter-base breakdown voltage (collector open)	$I_B = 1\text{ mA}$ ; $I_C = 0\text{ A}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$	15	19	-	V	
$V_{CEOsus}$	collector-emitter sustaining voltage (base open)	$I_B = 0\text{ A}$ ; $I_C = 10\text{ mA}$ ; $L_C = 25\text{ mH}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 6</a> ; <a href="#">Fig. 7</a>	[1]	400	470	V	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 1\text{ A}$ ; $I_B = 0.2\text{ A}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a> ; <a href="#">Fig. 9</a>	[1]	-	0.15	0.5	V
		$I_C = 3.5\text{ A}$ ; $I_B = 1\text{ A}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a> ; <a href="#">Fig. 9</a>	[1]	-	0.6	1.5	V
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 3.5\text{ A}$ ; $I_B = 1\text{ A}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>	[1]	-	1.1	1.5	V
$h_{FE}$	DC current gain	$I_C = 0.1\text{ A}$ ; $V_{CE} = 5\text{ V}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 11</a>	[1]	48	66	100	
		$I_C = 0.8\text{ A}$ ; $V_{CE} = 3\text{ V}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 12</a>	[1]	25	42	50	
<b>Dynamic characteristics</b>							
$t_s$	storage time	$I_C = 2.5\text{ A}$ ; $I_{B(on)} = 0.5\text{ A}$ ; $I_{B(off)} = -0.5\text{ A}$ ; $R_L = 60\text{ }\Omega$ ; $V_{BB} = -5\text{ V}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$ ; resistive load; $t_p = 300\text{ }\mu\text{s}$ ; <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>	-	-	3.5	$\mu\text{s}$	
$t_f$	fall time		-	-	500	ns	

[1] Pulse test: pulse duration  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$

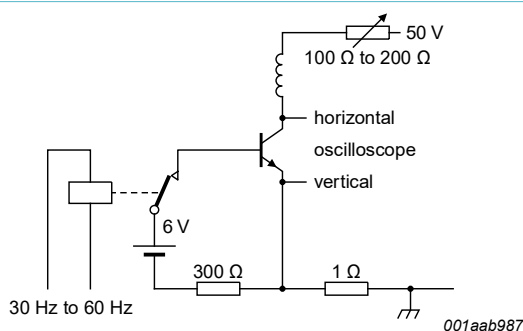


Fig. 6. Test circuit for collector-emitter sustaining voltage

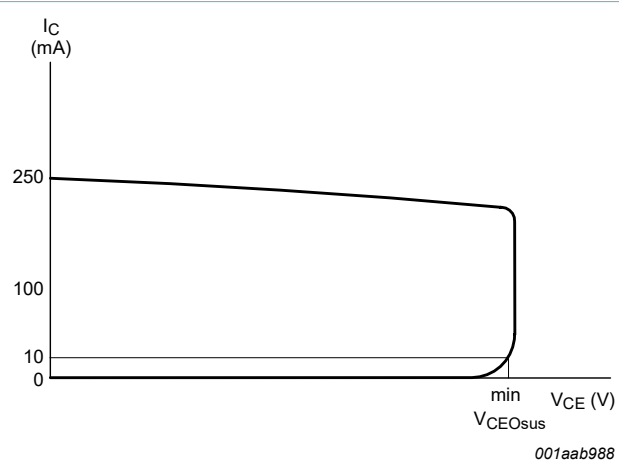


Fig. 7. Oscilloscope display for collector-emitter sustaining voltage test waveform

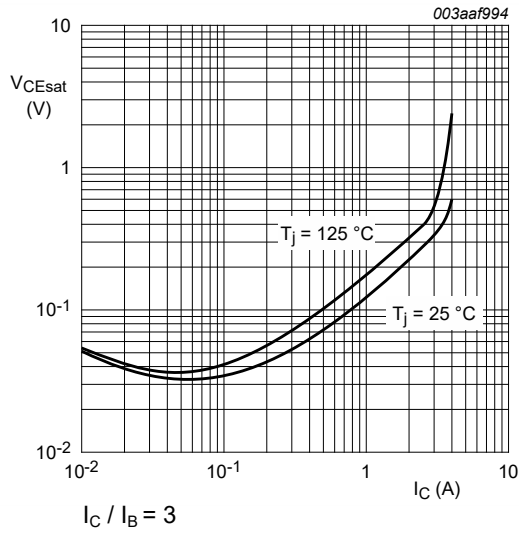


Fig. 8. Collector-emitter saturation voltage as a function of collector current; typical values

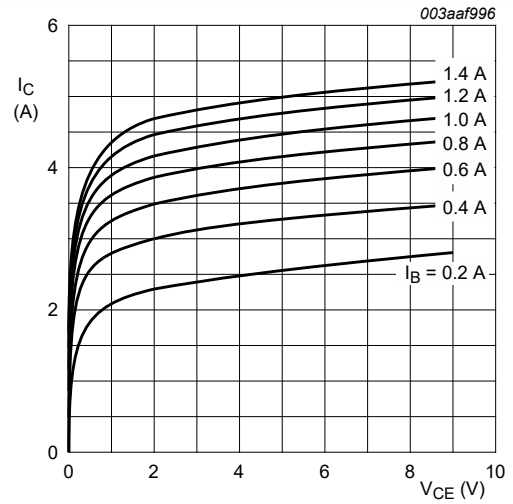


Fig. 9. Collector current as a function of collector-emitter voltage; typical values

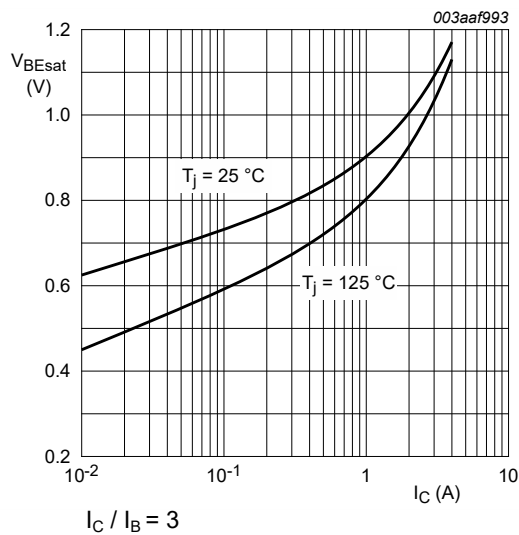


Fig. 10. Base-emitter saturation voltage as a function of collector current; typical values

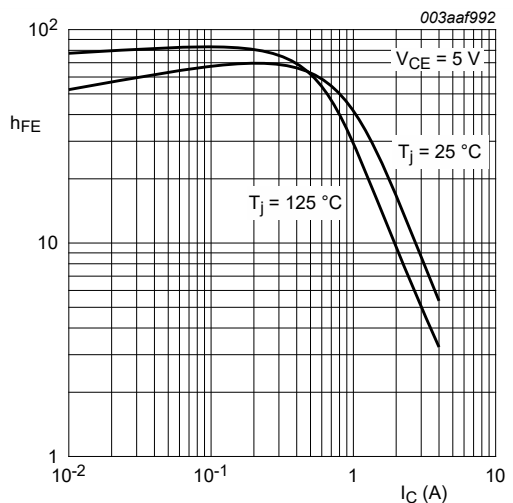


Fig. 11. DC current gain as a function of collector current; typical values

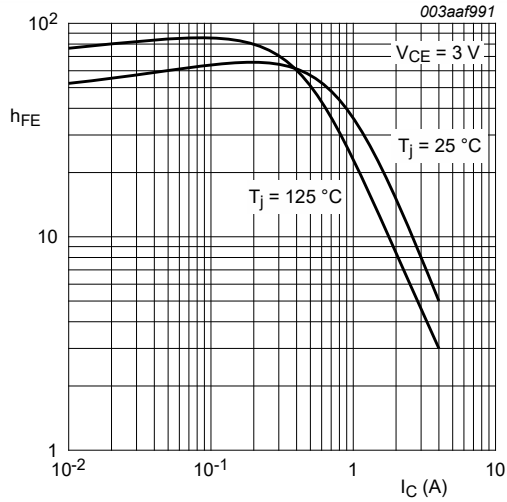
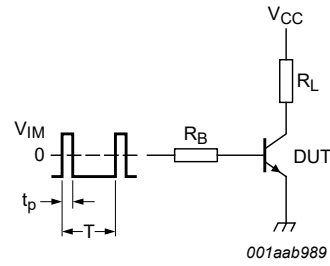


Fig. 12. DC current gain as a function of collector current; typical values



$V_{IM} = -6$  to  $+8$  V;  $V_{CC} = 250$  V;  $t_p = 20$   $\mu$ s;  $\delta = t_p/T = 0.01$   
 $R_B$  and  $R_L$  calculated from  $I_{Con}$  and  $I_{Bon}$  requirements.

Fig. 13. Test circuit for resistive load switching

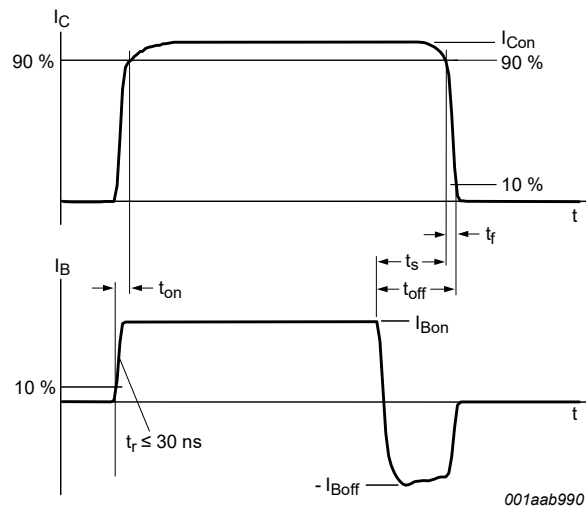
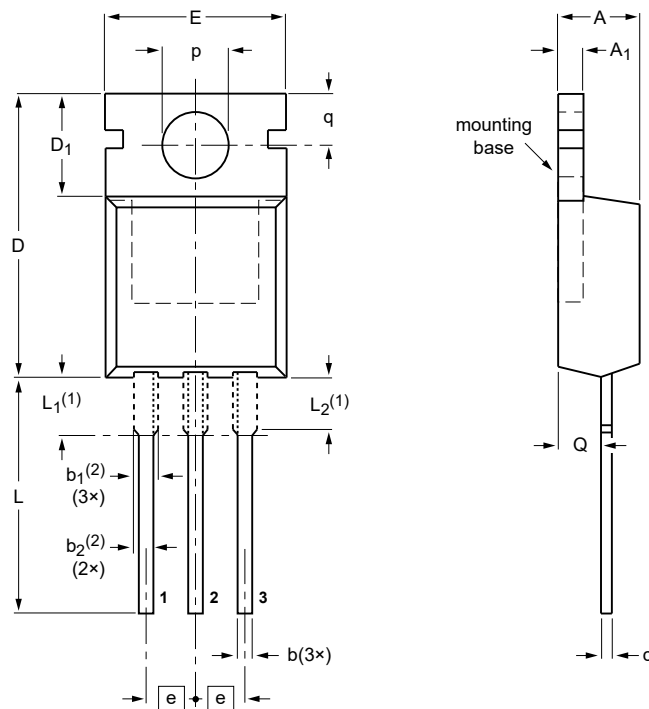


Fig. 14. Switching times waveforms for resistive load



### 10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB SOT78



**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub> (2)	b <sub>2</sub> (2)	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub> (1)	L <sub>2</sub> (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

**Notes**

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT78		3-lead TO-220AB	SC-46		08-04-23 08-06-13

**Fig. 15. Package outline TO-220AB (SOT78)**

## 11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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